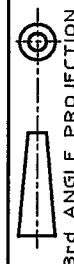


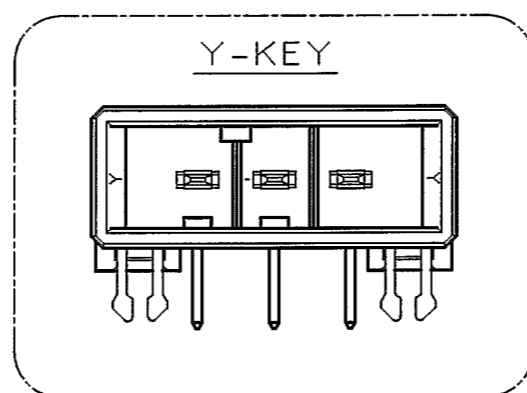
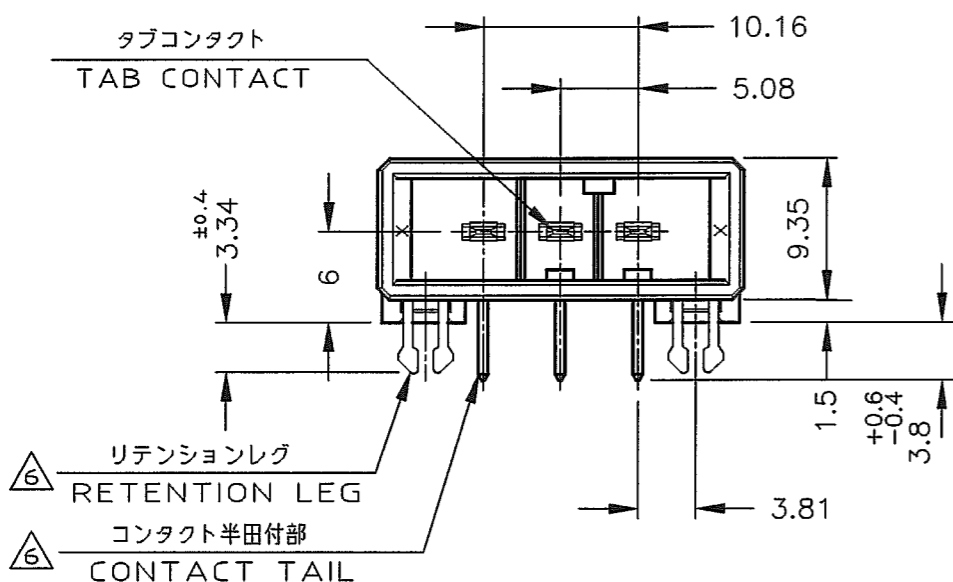
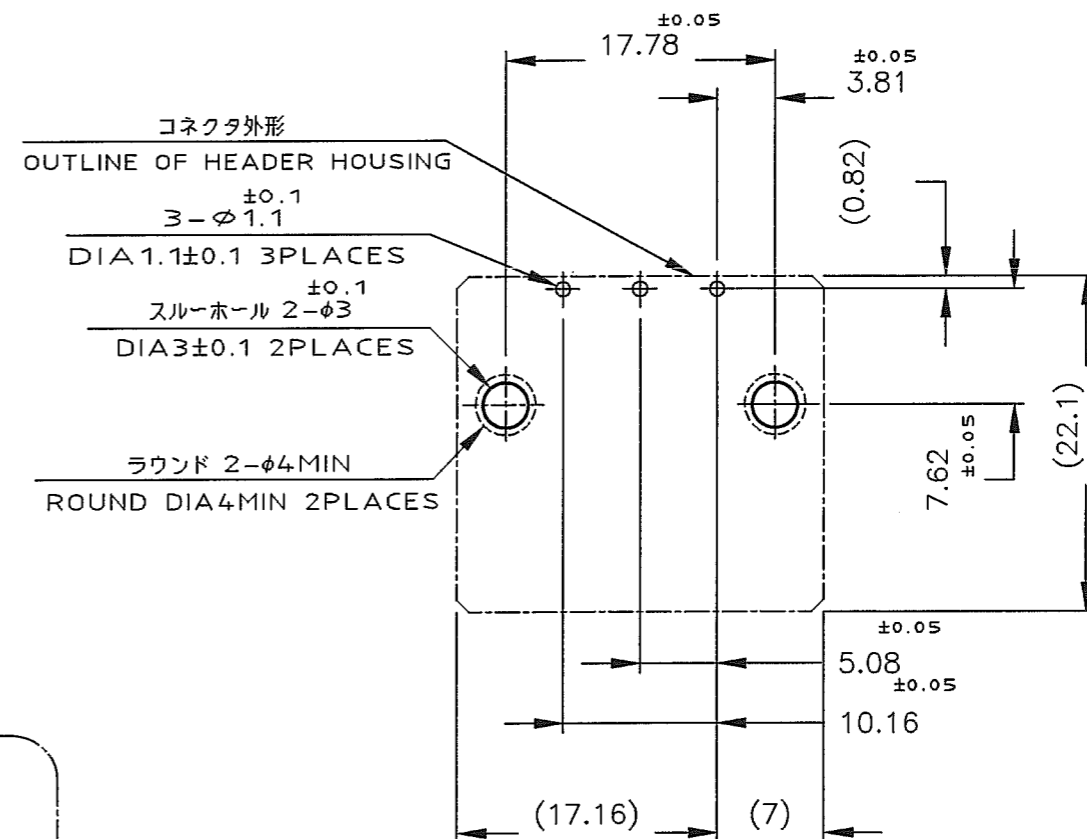
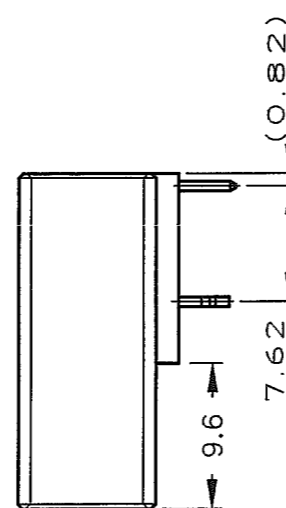
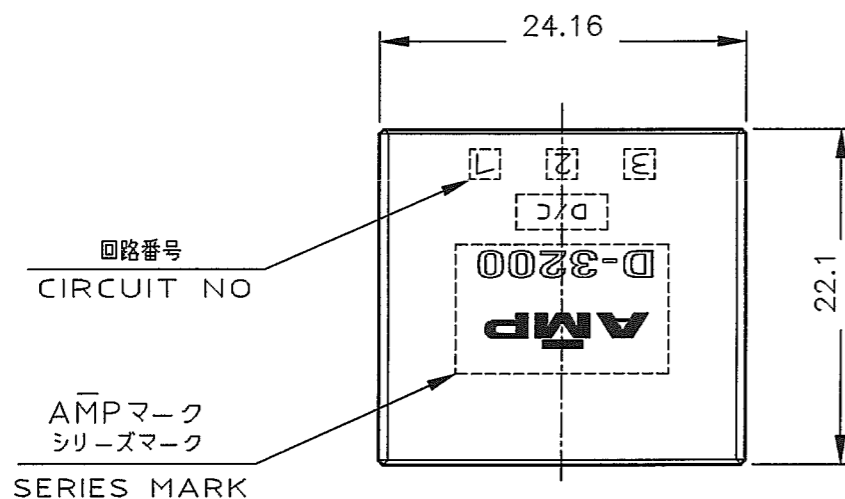
NUMBER 178138



METRIC

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST



推奨基板取付け寸法  
PC 基板厚: 1.6 ± 0.1  
(非累積公差)  
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN  
PC BOARD THICKNESS: 1.6 ± 0.1  
(NOT ACCUMULATE TOLERANCE)  
(CONNECTOR MOUNT SIDE)

- NOTES
- MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER  
CONTACT: COPPER ALLOY  
RETENTION LEG: COPPER ALLOY
  - FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
  - FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
  - FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
  - FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
  - FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

- 注記
- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂  
コンタクト: 銅合金  
リテンションレグ: 銅合金
  - めっき: コンタクト: 全面Ni下地  
接触部: 0.38 μm MIN金めっき
  - めっき: コンタクト: 全面Ni下地  
接触部: 0.76 μm MIN金めっき
  - めっき: コンタクト: 全面Ni下地  
接触部: 2.0 μm MINスズめっき
  - めっき: リテンションレグとコンタクト半田付部  
ニッケル下地の上に半田めっき
  - めっき: リテンションレグとコンタクト半田付部  
ニッケル下地の上にスズめっき

|          |    |                 |     |
|----------|----|-----------------|-----|
| △6       | △4 | 2-178138-5      | Y   |
| △6       | △3 | 2-178138-3      | Y   |
| △6       | △2 | 2-178138-2      | Y   |
| △6       | △4 | 1-178138-5      | X   |
| △6       | △3 | 1-178138-3      | X   |
| △6       | △2 | 1-178138-2      | X   |
| (FINISH) |    | 製品番号 (PART NO.) | KEY |

|                              |  |                            |   |                  |
|------------------------------|--|----------------------------|---|------------------|
| WIRE RANGE                   |  | INSULATION DIA             | NAME  |                  |
| mm <sup>2</sup> (AWG - )     |  | mmφ                        | 3 POS SINGLE ROW<br>HORIZONTAL HDR ASS'Y FOR DYNAMIC D-3200 |                  |
| MATERIAL<br>SEE NOTE<br>注記参照 |  | FINISH<br>SEE NOTE<br>注記参照 | 一般公差 (GENERAL TOLERANCE)                                    | SIZE LOC NUMBER  |
| DR. 20/MAR/95 K.IKEDA        |  | DE. 20/MAR/95 K.IKEDA      | 100F : ±0.3   | A3 J C-178138    |
| CHK. 23/MAR/95 S.MANABE      |  | APP. 23/MAR/95 S.MANABE    | 100F 300F : ±0.4  | SCALE REV. SHEET |
| E1 REVISED PER ECO-11-005030 |  | RK HMR 23/MAR/11           | 300F 1000F : ±0.5   | 2-1 E1 1 OF 1    |
| LTR REVISION RECORD          |  | DR CHK DATE                | 公差 : ±3'  |                  |

